



(1,27 mm) .050"

SEAM SERIES

HIGH SPEED/HIGH DENSITY OPEN PIN FIELD

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?SEAM

Insulator Material:

Black LCP

Contact Material:

Copper Alloy

Operating Temp Range:

-55°C to +125°C

Current Rating

(7 mm stack height):

1.8 A per pin

(10 adjacent pins powered)

Plating:

Au or Sn over

50µ" (1,27 µm) Ni

Contact Resistance: 5.5 mΩ

Working Voltage: 240 VAC

RoHS Compliant: Yes

Lead-Free Solderable: Yes

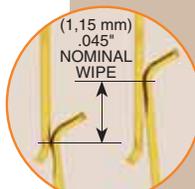
Mates with:
SEAF, SEAFP

Note: Patented

Note: Some sizes, styles and options are non-standard, non-returnable.



10 year Mixed Flowing Gas with 30µ" Gold Call Samtec for maximum mated cycles



Up to 500 Pins

5, 8 and 10 row footprint compatible with SamArray®. Samples recommended.

Low Insertion/Extraction Forces

Solder charges

SEAM/SEAF 10 mm Stack Height	Rated @ 3dB Insertion Loss	
	w/o PCB effects*	
Single-Ended Signaling	18 GHz / 36 Gbps	
Differential Pair Signaling	18 GHz / 36 Gbps	

*Test board losses de-embedded from performance data.
Performance data for other stack heights and complete test data available at www.samtec.com?SEAM or contact sig@samtec.com



28+ Gbps

RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality



Industry Standards

PISMO 2
VITA 47
VITA 57

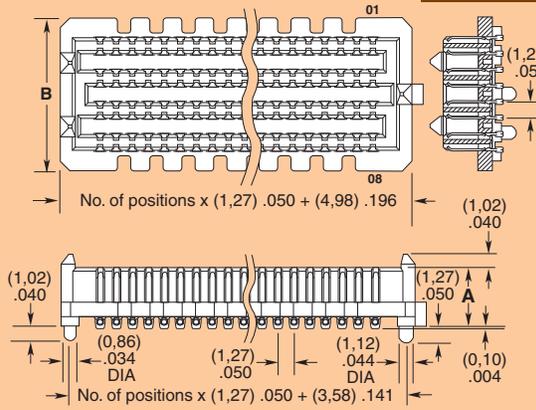
Protocols Supported

100 GbE
Fibre Channel
Rapid I/O
PCI Express®
SATA
InfiniBand™

Download app notes at www.samtec.com/appnote
Contact SIG @ samtec.com for questions on protocols

SEAM	NO. PINS PER ROW	LEAD STYLE	PLATING OPTION	NO. OF ROWS	SOLDER TYPE	A	K	TR
	-10, -15, -20, -30, -40, -50 (-10 only available in 04 row) (-15 only available in 10 row)	Specify LEAD STYLE from chart	-L = 10µ" (0,25 µm) Gold on contact area, Matte Tin on solder tail -S = 30µ" (0,76 µm) Gold on contact area, Matte Tin on solder tail	-04 = Four Rows (-06.5 not available) -05 = Five Rows (-06.5 not available) -06 = Six Rows (-06.5 not available) -08 = Eight Rows -10 = Ten Rows	-1 = Tin/Lead Alloy Solder Charge -2 = Lead-Free Solder Charge	-A = Alignment Pins (Required. Arrays will not self-center on solder pads) -K = Polyimide film Pick & Place Pad -TR = Tape & Reel		

NO. OF ROWS	B
-04	(7,06) .278
-05, -06	(9,60) .378
-08	(12,14) .478
-10	(14,68) .578



LEAD STYLE	A
-02.0	(4,60) .181
-03.0	(5,59) .220
-03.5	(6,10) .240
-06.5	(6,40) .252
-07.0	(9,60) .378
-09.0	(11,60) .457
-11.0	(13,60) .535

DIFFERENTIAL

ARRAY	PAIR COUNT
40x8	80
40x6	60
30x10	75
30x8	60
30x6	45
50x10	125
50x8	100
40x10	100

MATED HEIGHTS

SEAM LEAD STYLE	SEAF LEAD STYLE	-05.0	-06.0	-06.5
-02.0	7 mm	8 mm	8.5 mm	
-03.0	8 mm	9 mm	9.5 mm	
-03.5	8.5 mm	9.5 mm	10 mm	
-06.5	11.5 mm	12.5 mm	13 mm	
-07.0	12 mm	13 mm	13.5 mm	
-09.0	14 mm	15 mm	15.5 mm	
-11.0	16 mm	17 mm	17.5 mm	

Due to technical progress, all designs, specifications and components are subject to change without notice.

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